

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEONKOOK LEE	03/30/2016
LUA NGO	03/30/2016
BYONGHYO SHIM	03/31/2016
BYUNGJU LEE	03/31/2016
TAEYOUNG KIM	03/30/2016
JIYUN SEOL	03/30/2016
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
Name:	SEOUL NATIONAL UNIVERSITY R&DB FOUNDATION
Street Address:	1, GWANAK-RO, GWANAK-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15089397
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-628-3600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	SAMS06-16036

NAME OF SUBMITTER:	JACOB L. LACOMBE
SIGNATURE:	/Jacob L. LaCombe/
DATE SIGNED:	04/01/2016
Total Attachments: 8 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif source=Assignment#page8.tif	

ASSIGNMENT

WHEREAS, We, Keonkook Lee, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Lua Ngo, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Vietnam, Byonghyo Shim, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Byungju Lee, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Taeyoung Kim, resident of Gangnam-gu, Seoul, Republic of Korea, citizen of Republic of Korea, and Jiyun Seol, resident of Seongnam-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a “.” disclosed in an application for United States Letters Patent (Application Serial No. ___/_____, filed on _____), said application having been executed concurrently herewith;

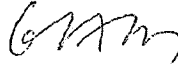
WHEREAS, SAMSUNG ELECTRONICS CO., LTD, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea and SEOUL NATIONAL UNIVERSITY R&DB FOUNDATION, having a place of business at 1, Gwanak-ro, Gwanak-gu, Seoul, Republic of Korea (hereinafter referred to as “ASSIGNEES”), are desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEES, their successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEES of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEES, their successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEES, their successors, assigns and legal representatives.

We hereby further agree that we will communicate to said ASSIGNEES, or to their successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEES, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEES and to aid said ASSIGNEES, their successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: 2016. 3. 30



KEONKOOK LEE

Date: _____

LUA NGO

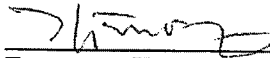
Date: _____

BYONGHYO SHIM

Date: _____

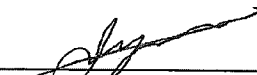
BYUNGJU LEE

Date: 2016. 3. 30



TAEYOUNG KIM

Date: 2016. 3. 30



JYUN SEOL

ASSIGNMENT

WHEREAS, We, Keonkook Lee, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Lua Ngo, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Vietnam, Byonghyo Shim, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Byungju Lee, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Taeyoung Kim, resident of Gangnam-gu, Seoul, Republic of Korea, citizen of Republic of Korea, and Jiyun Seol, resident of Seongnam-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a “.” disclosed in an application for United States Letters Patent (Application Serial No. ___/_____, filed on _____), said application having been executed concurrently herewith;

WHEREAS, SAMSUNG ELECTRONICS CO., LTD, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea and SEOUL NATIONAL UNIVERSITY R&DB FOUNDATION, having a place of business at 1, Gwanak-ro, Gwanak-gu, Seoul, Republic of Korea (hereinafter referred to as “ASSIGNEES”), are desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEES, their successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEES of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEES, their successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEES, their successors, assigns and legal representatives.

We hereby further agree that we will communicate to said ASSIGNEES, or to their successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEES, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEES and to aid said ASSIGNEES, their successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: _____

KEONKOOK LEE

Date: March 30, 2016



LUA NGO

Date: _____

BYONGHYO SHIM

Date: _____

BYUNGU LEE

Date: _____

TAEYOUNG KIM

Date: _____

JIYUN SEOL

ASSIGNMENT

WHEREAS, We, Keonkook Lee, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Lua Ngo, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Vietnam, Byonghyo Shim, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Byungju Lee, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Taeyoung Kim, resident of Gangnam-gu, Seoul, Republic of Korea, citizen of Republic of Korea, and Jiyun Seol, resident of Seongnam-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a “.” disclosed in an application for United States Letters Patent (Application Serial No. ___/_____, filed on _____), said application having been executed concurrently herewith;

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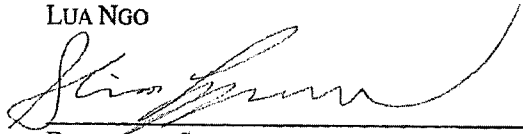
NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEES, their successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEES of our entire right, title and interest.

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Date: _____
_____ KEONKOOK LEE

Date: _____
_____ LUA NGO

Date: 2016/03/31 _____
_____  BYONGHYO SHIM

Date: _____
_____ BYUNGU LEE

Date: _____
_____ TAEYOUNG KIM

Date: _____
_____ JIYUN SEOL

ASSIGNMENT

WHEREAS, We, Keonkook Lee, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Lua Ngo, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Vietnam, Byonghyo Shim, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Byungju Lee, resident of Gwanak-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Taeyoung Kim, resident of Gangnam-gu, Seoul, Republic of Korea, citizen of Republic of Korea, and Jiyun Seol, resident of Seongnam-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a “.” disclosed in an application for United States Letters Patent (Application Serial No. ___/_____, filed on _____), said application having been executed concurrently herewith;

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Date: _____
KEONKOOK LEE

Date: _____
LUA NGO

Date: _____
BYONGHYO SHIM

Date: 03/31/2016
Lee Byungju
BYUNGJU LEE

Date: _____
TAEYOUNG KIM

Date: _____
JIYUN SEOL